

## 27. Ordering Information<sup>(2)</sup>

### 27.1 Standard Package

t <sub>Acc</sub> (ns)	I <sub>cc</sub> (mA)		Ordering Code	Package	Operation Range	
	Active	Standby				
150	50	0.2	AT28C256(E,F)-15JC	32J	Commercial (0°C to 70°C)	
			AT28C256(E,F)-15PC	28P6		
			AT28C256(E,F)-15SC	28S		
			AT28C256(E,F)-15TC	28T		
			AT28C256(E,F)-15JI	32J		Industrial (-40°C to 85°C)
			AT28C256(E,F)-15PI	28P6		
			AT28C256(E,F)-15SI	28S		
			AT28C256(E,F)-15TI	28T		
	50	0.3	AT28C256(E,F)-15DM/883	28D6	Military/883C Class B, Fully Compliant (-55°C to 125°C)	
			AT28C256(E,F)-15FM/883	28F		
			AT28C256(E,F)-15LM/883	32L		
			AT28C256(E,F)-15UM/883	28U		
200	50	0.2	AT28C256(E,F)-20JC	32J	Commercial (0°C to 70°C)	
			AT28C256(E,F)-20PC	28P6		
			AT28C256(E,F)-20SC	28S		
			AT28C256(E,F)-20TC	28T		
			AT28C256(E,F)-20JI	32J		Industrial (-40°C to 85°C)
			AT28C256(E,F)-20PI	28P6		
			AT28C256(E,F)-20SI	28S		
			AT28C256(E,F)-20TI	28T		
	50	0.3	AT28C256(E,F)-20DM/883	28D6	Military/883C Class B, Fully Compliant (-55°C to 125°C)	
			AT28C256(E,F)-20FM/883	28F		
			AT28C256(E,F)-20LM/883	32L		
			AT28C256(E,F)-20UM/883	28U		

Package Type	
<b>28D6</b>	28-lead, 0.600" Wide, Non-windowed, Ceramic Dual Inline Package (Cerdip)
<b>28F</b>	28-lead, Non-windowed, Ceramic Bottom-brazed Flat Package (Flatpack)
<b>32J</b>	32-lead, Plastic J-leaded Chip Carrier (PLCC)
<b>32L</b>	32-pad, Non-windowed, Ceramic Leadless Chip Carrier (LCC)
<b>28P6</b>	28-lead, 0.600" Wide, Plastic Dual Inline Package (PDIP)
<b>28S</b>	28-lead, 0.300" Wide, Plastic Gull Wing Small Outline (SOIC)
<b>28T</b>	28-lead, Plastic Thin Small Outline Package (TSOP)
<b>28U</b>	28-pin, Ceramic Pin Grid Array (PGA)
<b>W</b>	Die
Options	
<b>Blank</b>	Standard Device: Endurance = 10K Write Cycles; Write Time = 10 ms
<b>E</b>	High Endurance Option: Endurance = 100K Write Cycles
<b>F</b>	Fast Write Option: Write Time = 3 ms

## 27.1 Standard Package (Continued)

t <sub>Acc</sub> (ns)	I <sub>CC</sub> (mA)		Ordering Code	Package	Operation Range		
	Active	Standby					
250	50	0.2	AT28C256(E,F)-25JC	32J	Commercial (0°C to 70°C)		
			AT28C256(E,F)-25PC	28P6			
			AT28C256-W	DIE			
	50	0.3	AT28C256(E,F)-25JI	32J	Industrial (-40°C to 85°C)		
			AT28C256(E,F)-25PI	28P6			
			AT28C256(E,F)-25DM/883	28D6		Military/883C Class B, Fully Compliant (-55°C to 125°C)	
AT28C256(E,F)-25FM/883	28F						
AT28C256(E,F)-25LM/883	32L						
150 <sup>(3)</sup>	50	0.3	AT28C256(E,F)-25UM/883	28U	Military/883C Class B, Fully Compliant (-55°C to 125°C)		
			AT28C256(E,F)-35UM/883	28U			
			5962-88525 16 UX	28U		Military/883C Class B, Fully Compliant (-55°C to 125°C)	
			5962-88525 16 XX	28D6			
			5962-88525 16 YX	32L			
			5962-88525 16 ZX	28F		Military/883C Class B, Fully Compliant (-55°C to 125°C)	
	5962-88525 15 UX	28U					
	5962-88525 15 XX	28D6					
	150 <sup>(3)</sup>	50	0.3	5962-88525 15 YX	32L	Military/883C Class B, Fully Compliant (-55°C to 125°C)	
				5962-88525 15 ZX	28F		
				5962-88525 14 UX	28U		Military/883C Class B, Fully Compliant (-55°C to 125°C)
				5962-88525 14 XX	28D6		
5962-88525 14 YX				32L			
5962-88525 14 ZX				28F	Military/883C Class B, Fully Compliant (-55°C to 125°C)		

Package Type	
<b>28D6</b>	28-lead, 0.600" Wide, Non-windowed, Ceramic Dual Inline Package (Cerdip)
<b>28F</b>	28-lead, Non-windowed, Ceramic Bottom-brazed Flat Package (Flatpack)
<b>32J</b>	32-lead, Plastic J-leaded Chip Carrier (PLCC)
<b>32L</b>	32-pad, Non-windowed, Ceramic Leadless Chip Carrier (LCC)
<b>28P6</b>	28-lead, 0.600" Wide, Plastic Dual Inline Package (PDIP)
<b>28U</b>	28-pin, Ceramic Pin Grid Array (PGA)
<b>W</b>	Die
Options	
<b>Blank</b>	Standard Device: Endurance = 10K Write Cycles; Write Time = 10 ms
<b>E</b>	High Endurance Option: Endurance = 100K Write Cycles
<b>F</b>	Fast Write Option: Write Time = 3 ms

**27.1 Standard Package (Continued)**

t <sub>Acc</sub> (ns)	I <sub>CC</sub> (mA)		Ordering Code	Package	Operation Range	
	Active	Standby				
150 <sup>(3)</sup>	50	0.3	5962-88525 08 UX	28U	Military/883C Class B, Fully Compliant (-55°C to 125°C)	
			5962-88525 08 XX	28D6		
			5962-88525 08 YX	32L		
			5962-88525 08 ZX	28F		
				5962-88525 07 UX	28U	Military/883C Class B, Fully Compliant (-55°C to 125°C)
				5962-88525 07 XX	28D6	
				5962-88525 07 YX	32L	
				5962-88525 07 ZX	28F	
				5962-88525 06 UX	28U	Military/883C Class B, Fully Compliant (-55°C to 125°C)
				5962-88525 06 XX	28D6	
				5962-88525 06 YX	32L	
				5962-88525 06 ZX	28F	
200 <sup>(3)</sup>	50	0.3	5962-88525 12 UX	28U	Military/883C Class B, Fully Compliant (-55°C to 125°C)	
			5962-88525 12 XX	28D6		
			5962-88525 12 YX	32L		
			5962-88525 12 ZX	28F		
		50	0.3	5962-88525 04 UX	28U	Military/883C Class B, Fully Compliant (-55°C to 125°C)
				5962-88525 04 XX	28D6	
				5962-88525 04 YX	32L	
				5962-88525 04 ZX	28F	
250 <sup>(3)</sup>	50	0.3	5962-88525 13 UX	28U	Military/883C Class B, Fully Compliant (-55°C to 125°C)	
			5962-88525 13 XX	28D6		
			5962-88525 13 YX	32L		
			5962-88525 13 ZX	28F		
				5962-88525 11 UX	28U	Military/883C Class B, Fully Compliant (-55°C to 125°C)
				5962-88525 11 XX	28D6	
				5962-88525 11 YX	32L	
				5962-88525 11 ZX	28F	

Package Type	
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<b>28F</b>	28-lead, Non-windowed, Ceramic Bottom-brazed Flat Package (Flatpack)
<b>32L</b>	32-pad, Non-windowed, Ceramic Leadless Chip Carrier (LCC)
<b>28U</b>	28-pin, Ceramic Pin Grid Array (PGA)
<b>W</b>	Die
Options	
<b>Blank</b>	Standard Device: Endurance = 10K Write Cycles; Write Time = 10 ms
<b>E</b>	High Endurance Option: Endurance = 100K Write Cycles
<b>F</b>	Fast Write Option: Write Time = 3 ms